

IN THE SPECIFICATION

Please insert the following paragraph on page 1, before the Background Of the Invention:

The present patent application is a divisional of Application No.: 10/023,073 filed December 20, 2001 which is currently pending.

Please amend the following paragraphs in the specification:

[0014] In the embodiment shown in FIG. 1, the entire surface of body 30 is coated. In other embodiments, however, the surface of the heat spreader may be partially coated. Additionally, FIG. 1 shows an optional metal coating 25 that has been plated onto the heat spreader before the application of the OSP 20. This metal coating can be Ni or Pd.

[0017] FIG. 2 shows an embodiment of an IC package containing coated heat spreader 10. Flip chip die 15 is mounted on package substrate 40 via die bumps and underfill 18. Alternatively, die 15 may be configured for mounting by other means besides a ball grid array (BGA"). For example, flip chip die 15 may be mounted by a pin grid array ("PGA"). The flip chip die may be any active or passive electronic device, e.g., a microprocessor or a memory chip. Package substrate 40 includes pads 65 and solder bumps 70 for mounting to a PCB 85. In other embodiments, substrate 40 may be mounted to a PCB 85 by other means.